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# FDMS86202ET120

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January 2015

# N-Channel Shielded Gate PowerTrench® MOSFET 120 V, 102 A, 7.2 m $\Omega$

#### **Features**

- Extended T<sub>J</sub> rating to 175°C
- Shielded Gate MOSFET Technology
- Max  $r_{DS(on)} = 7.2 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 13.5 \text{ A}$
- Max  $r_{DS(on)} = 10.3 \text{ m}\Omega$  at  $V_{GS} = 6 \text{ V}$ ,  $I_D = 11.5 \text{ A}$
- Advanced Package and Silicon combination for low r<sub>DS(on)</sub> and high efficiency
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

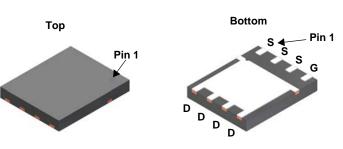


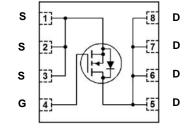
# **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

# **Application**

■ DC-DC Conversion





Power 56

## MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Parame	ter		Ratings	Units
$V_{DS}$	Drain to Source Voltage			120	V
$V_{GS}$	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T <sub>C</sub> = 25 °C	(Note 5)	102	
	-Continuous	T <sub>C</sub> = 100 °C	(Note 5)	72	A
ID	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	13.5	_ ^
	-Pulsed		(Note 4)	538	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	600	mJ
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25 °C		187	W
	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	3.3	VV
$T_J, T_{STG}$	Operating and Storage Junction Temperat	ture Range		-55 to +175	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.8	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	45	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86202ET	FDMS86202ET120	Power 56	13 "	12 mm	3000 units

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Тур

Max

Units

Min

# Electrical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

**Parameter** 

Off Characteristics									
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	120			V			
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		103		mV/°C			
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 96 V, V <sub>GS</sub> = 0 V			1	μΑ			
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA			

**Test Conditions** 

#### On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250 \mu A$	2.0	3.1	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, referenced to 25 °C		-10		mV/°C
r <sub>DS(on)</sub>		$V_{GS} = 10 \text{ V}, I_D = 13.5 \text{ A}$		6.0	7.2	
		$V_{GS} = 6 \text{ V}, I_D = 11.5 \text{ A}$		8.1	10.3	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 13.5 \text{ A}, T_J = 125 \text{ °C}$		10.9	13.2	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 13.5 A		44		S

# **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, f = 1 MHz		3275	4585	pF
Coss	Output Capacitance			460	644	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			17	30	pF
$R_g$	Gate Resistance		0.1	0.9	2.7	Ω

## **Switching Characteristics**

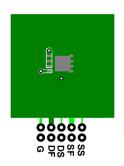
t <sub>d(on)</sub>	Turn-On Delay Time			21	33	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 60 \text{ V}, I_{D} = 13.$	.5 A,	8.75	17.5	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10 V, R <sub>GEN</sub> =	: 6 Ω	27.2	44	ns
t <sub>f</sub>	Fall Time			6.1	12.2	ns
$Q_q$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 10 \text{ V}$		45	64	nC
$Q_q$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 6 \text{ V}$	V <sub>DD</sub> = 60 V,	29	41	nC
$Q_{gs}$	Gate to Source Charge		I <sub>D</sub> = 13.5 A	14.3		nC
$Q_{qd}$	Gate to Drain "Miller" Charge			9.5		nC

#### **Drain-Source Diode Characteristics**

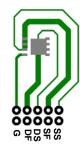
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2.1 \text{ A}$ (Note 2)	0.69	1.2	V
		$V_{GS} = 0 \text{ V}, I_S = 13.5 \text{ A}$ (Note 2)	0.76	1.3	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>E</sub> = 13.5 A, di/dt = 100 A/μs	79	127	ns
Q <sub>rr</sub>	Reverse Recovery Charge	TIF = 13.5 A, αΙ/αι = 100 A/μs	140	224	nC

#### Notes:

<sup>1.</sup> R<sub>0JA</sub> is determined with the device mounted on a 1in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0CA</sub> is determined by the user's board design.



a) 45 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



 b) 115 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300  $\mu\text{s}$  , Duty cycle < 2.0%.
- 3.  $E_{AS}$  of 600 mJ is based on starting  $T_J$  = 25 °C, L = 3 mH,  $I_{AS}$  = 20 A,  $V_{DD}$  = 120 V,  $V_{GS}$  = 10 V. 100% test at L = 0.1 mH,  $I_{AS}$  = 65 A.
- 4. Pulse Id please refer to Fig.11 SOA curve for detail.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

## Typical Characteristics T<sub>.I</sub> = 25 °C unless otherwise noted

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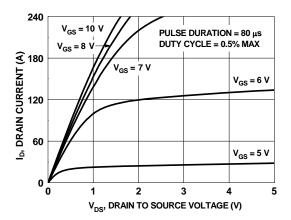


Figure 1. On Region Characteristics

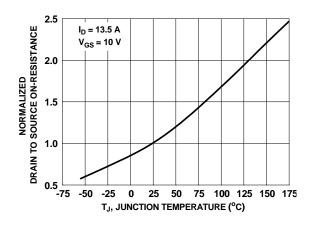


Figure 3. Normalized On Resistance vs Junction Temperature

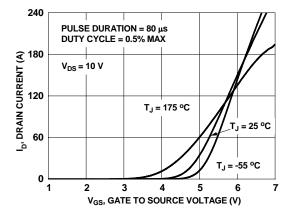


Figure 5. Transfer Characteristics

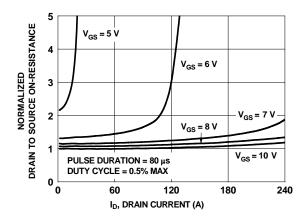


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

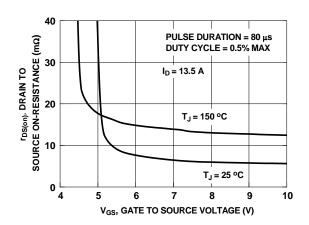


Figure 4. On-Resistance vs Gate to Source Voltage

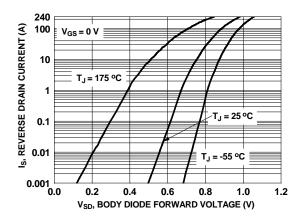


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

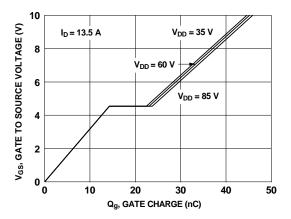


Figure 7. Gate Charge Characteristics

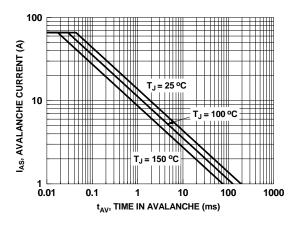


Figure 9. Unclamped Inductive Switching Capability

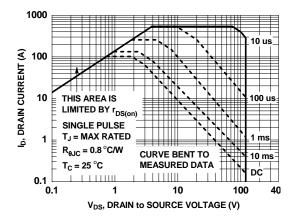


Figure 11. Forward Bias Safe Operating Area

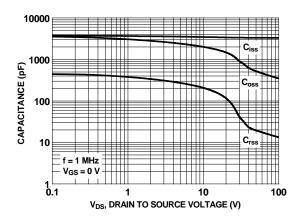


Figure 8. Capacitance vs Drain to Source Voltage

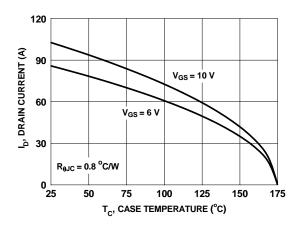


Figure 10. Maximum Continuous Drain Current vs Case Temperature

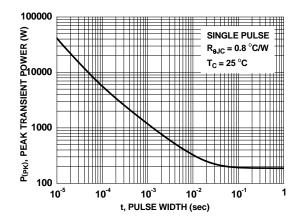


Figure 12. Single Pulse Maximum Power Dissipation

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

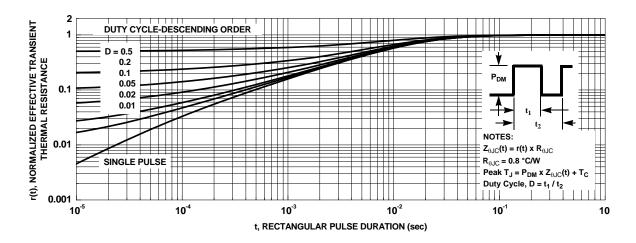
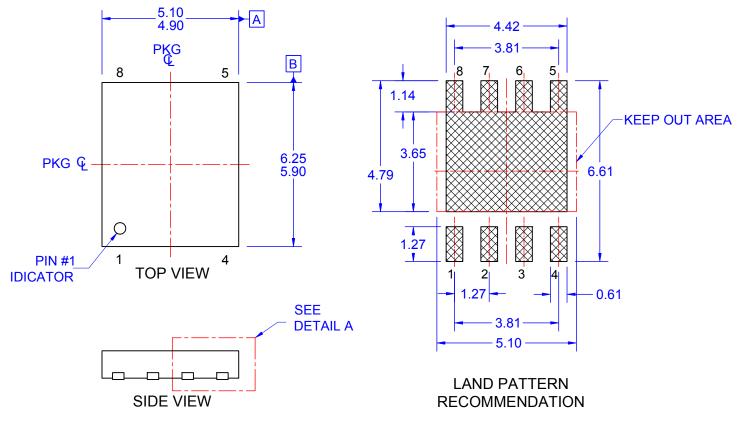
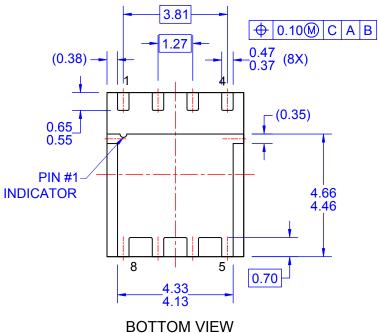


Figure 13. Junction-to-Ambient Transient Thermal Response Curve





0.10 C
1.10
0.90
0.08 C
0.25
0.05
0.00
SEATING
PLANE
DETAIL A

SCALE: 2:1

NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. AA,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
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